#### 501927590 05/21/2012

#### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Masaki HANEDA	03/14/2012
Yuka KASE	02/29/2012
Masanori TERAHARA	02/28/2012
Takayuki AOYAMA	03/01/2012

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### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13440506

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ATTORNEY DOCKET NUMBER:	111678
NAME OF SUBMITTER:	Stephen G. Adrian

### Total Attachments: 3

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> PATENT REEL: 028241 FRAME: 0509

TOP \$40.00 13440506

# U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (Insert Name(s) & Address(es) of ASSIGNEE(S))

	Fujitsu Semiconductor Limite	ed					
	2-10-23 Shin-Yokohama, Ko	hoku-ku, Yokohama	r-shi, Kanagawa 22	2-0033	Japan	***************************************	<del>/////////////////////////////////////</del>
ass	ereinafter, "ASSIGNEE"), the receipsigns and transfers to ASSIGNEE the of Invention)	pt of which is hereby a the entire and exclusi	cknowledged, the und re right, title and intere	ersigne est to th	d ASSIG	NOR here	by sell
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rela	ating to International Patent Applic the United States was executed or	ation PCT/JP/ n even date herewith c	and/or for w	hich ap vas:	plication	for Letters	Paten
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cor terr	d to said application and all Letters ntinuation, division, renewal, subst ms for which the said Letters Pate reinafter, "said application(s) and L	itute, reissue or reexai nt(s) may be granted a	nination application b	ased th	erean fo	r the full to	rm or
ma apr pro act	The ASSIGNOR agree(s), when re SIGNEE, to do all acts which the A intaining and enforcing protection blication(s) and the issuance of sai ceeding, and in any litigation or out to include but not be limited to ex intil oaths, providing sworn testime	ASSIGNEE may deem for said invention, incl id Letters Patent(s), in her legal proceeding w ecuting all papers, incl	necessary, desirable uding in the preparation any interference, reis thich may arise or be uding separate assign	or expension and particular or expension of the contraction of the con	edient, fo prosecuti examinati	securing, on of said on, or pub	lic use
	IN WITNESS WHEREOF, the und			ner/their	signatur	e(s).	
1)	Masaki Haneda	Masaki Ha	aneda	Mar.	14 +1	2012	
	( Signature)	(Type Na	ne)		(Date	2012	•
2)	•	Yuka K	ase				
-	( Signature)	(Type Nai	ne)		(Date	<del>,</del>	ı
3)		Masanori To	erahara				
-	( Signature)	(Type Nai			(Date	)	
4)	•	Takayuki A	ovama		,	•	
-	( Signature)	(Type Nar			(Date	)	

## U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (Insert Name(s) & Address(es) of ASSIGNEE(S)) Fujitsu Semiconductor Limited 2-10-23 Shin-Yokohama, Kohoku-ku, Yokohama-shi, Kanagawa 222-0033 Japan (hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled (Title of Invention) SEMICONDUCTOR DEVICE AND FABRICATION METHOD relating to International Patent Application PCT/JP and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was: (a) executed on (Insert date of execution of application, if not concurrent) (b) filed on Assignee's attorney is hereby authorized to Serial No. insert in (b) the specified data, when known. and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)"). The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence. IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s). Masaki Haneda (Type Name) Yuka Kase (Type Name) Masanori Terahara (Type Name)

Takayuki Aoyama

(Type Name)

( Signature)

(Date)

## U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (insert Name(s) & Address(es) of ASSIGNEE(S))

Fujitsu Semiconductor Limit		
2-10-23 Shin-Yokohama, Ko	choku–ku, Yokohama–shi	, Kanagawa 222-0033 Japan
hereinafter, "ASSIGNEE"), the rece ssigns and transfers to ASSIGNEE Title of Invention)	ipt of which is hereby acknow the entire and exclusive rig	wledged, the undersigned ASSIGNOR hereby se tht, title and interest to the invention entitled
SEMICONDUCTOR DEVICE	E AND FABRICATION	METHOD
elating to International Patent Applic of the United States was executed o	cation PCT/JP <u>/</u> n even date herewith or, if r	and/or for which application for Letters Pate
(a) executed on		ert date of execution of application, if not current)
(b) filed on	As	ssignee's attorney is hereby authorized to rt in (b) the specified data, when known.
ASSIGNEE, to do all acts which the naintaining and enforcing protection application(s) and the issuance of sa proceeding, and in any litigation or o	ASSIGNEE may deem neon for said invention, including aid Letters Patent(s), in any ther legal proceeding which executing all papers, including	EE and without charge to but at the expense of sessary, desirable or expedient, for securing, g in the preparation and prosecution of said interference, reissue, reexamination, or public umay arise or be declared in relation to same, suggested as a second declarations, taking despense and declarations, taking
		nave) affixed his/her/their signature(s).
)	· Masaki Haned	a .
( Signature)	(Type Name)	(Date)
e)	Yuka Kase	
( Signature)	(Type Name)	(Date)
)	Masanori Terah	
( Signature)	(Type Name)	(Date)
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/ (Signeture)	(Type Name)	(Date)
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PATENT REEL: 028241 FRAME: 0512

RECORDED: 05/21/2012